

High Speed 8-Bit TTL A/D Converter

AD9012

FEATURES
100 MSPS Encode Rate

Very Low Input Capacitance—16 pF Low Power—1 W

Low Power—1 w

TTL Compatible Outputs

MIL-STD-883 Compliant Versions Available

APPLICATIONS

Radar Guidance

Digital Oscilloscopes/ATE Equipment

Laser/Radar Warning Receivers

Digital Radio

Electronic Warfare (ECM, ECCM, ESM)

Communication/Signal Intelligence

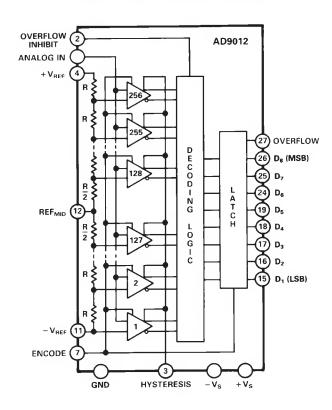
GENERAL DESCRIPTION

The AD 9012 is an 8-bit, ultrahigh speed, analog-to-digital converter. The AD 9012 is fabricated in an advanced bipolar process that allows operation at sampling rates up to one hundred megasamples/second. Functionally, the AD 9012 is comprised of 256 parallel comparator stages whose outputs are decoded to drive the TTL compatible output latches.

The exceptionally wide large-signal analog input bandwidth of 160 MHz is due to an innovative comparator design and very close attention to device layout considerations. The wide input bandwidth of the AD 9012 allows very accurate acquisition of high speed pulse inputs without an external track-and-hold. The comparator output decoding scheme minimizes false codes, which is critical to high speed linearity.

The AD 9012 is available in two grades: one with 0.5 LSB linearity and one with 0.75 LSB linearity. Both versions are offered in an industrial grade, -25°C to +85°C, packaged in a 28-pin DIP

FUNCTIONAL BLOCK DIAGRAM



and a 28-pin JLCC. The military temperature range devices, -55°C to $+125^{\circ}\text{C}$, are available in ceramic DIP and LCC packages and are compliant to MIL-STD-883 Class B.

The AD 9012 is available in versions compliant with MIL-STD-883. Refer to the Analog D evices M ilitary Products D atabook or current AD 9012/883B data sheet for detailed specifications.

AD9012- SPECIFICATIONS

ELECTRICAL CHARACTERISTICS (+ $V_s = +5.0 \text{ V}$; - $V_s = -5.2 \text{ V}$; Differential Reference Voltage = 2.0 V; unless otherwise noted)

Parameter	Temp	Test Level		9012A0 Typ	Q/AJ Max	AD Min	9012B (Q/BJ Max		9012SC Typ)/SE Max		9012T (Units
RESOLUTION			8			8			8			8			Bits
DC ACCURACY Differential Linearity Integral Linearity	+25°C Full +25°C Full	I VI I VI		0.6	0.75 1.0 1.0 1.2		0.4	0.5 0.75 0.5 1.2		0.6	0.75 1.0 1.0 1.2		0.4	0.5 0.75 0.5 1.2	LSB LSB LSB LSB
N o M issing C odes	Full	νi	GUA	RANTE		GU	ARANT		GU	ARAN		GU	ARAN		235
INITIAL OFFSET ERROR T op of Reference Ladder Bottom of Reference Ladder Offset D rift C oefficient	+25°C Full +25°C Full Full	I VI I VI V		7 6 25	15 18 10 13		7 6 25	15 18 10 13		7 6 25	15 18 10 13		7 6 25	15 18 10 13	mV mV mV mV μV/°C
ANALOG INPUT Input Bias Current ¹ Input Resistance Input Capacitance Large Signal Bandwidth ² Analog Input Slew Rate ³	+25°C Full +25°C +25°C +25°C +25°C	I VI I III V	150	200 16 160 440	100 200 18	150	200 16 160 440	100 200 18	150	60 200 16 160 440	100 200 18	150	60 200 16 160 440	100 200 18	μΑ μΑ kΩ pF M H z V/μs
REFERENCE INPUT Reference Ladder Resistance Ladder Temperature Coefficient Reference Input Bandwidth	+25°C +25°C	VI V V	64	80 0.25 10	110	64	80 0.25 10	110	64	80 0.25 10	110	64	80 0.25 10	110	Ω Ω/°C M H z
DYNAMIC PERFORMANCE Conversion Rate Aperture D elay Aperture Uncertainty (Jitter) Output D elay (t _{PD}) ^{4, 5} T ransient Response ⁶ O vervoltage R ecovery T ime ⁷ Output R ise T ime ⁴ Output T ime Skew ^{4, 8}	+25°C +25°C +25°C +25°C +25°C +25°C +25°C +25°C +25°C	V	75 4	100 3.8 15 4.9 8 8 6.6 3.3 3.0	11 8.0 4.3	75 4	100 3.8 15 4.9 8 6.6 3.3 3.0	11 8.0 4.3	75 4	100 3.8 15 4.9 8 6.6 3.3 3.0	11 8.0 4.3	75 4	100 3.8 15 4.9 8 8 6.6 3.3 3.0	11 8.0 4.3	M SPS ns ps ns ns ns ns
ENCODE INPUT Logic "1" Voltage ⁴ Logic "0" Voltage ⁴ Logic "1" Current Logic "0" Current Input Capacitance Encode Pulse Width (Low) ⁹ Encode Pulse Width (High) ⁹	Full Full Full +25°C +25°C +25°C	VI VI VI VI V	2.0 2.5 2.5	2.5	0.8 250 400	2.0 2.5 2.5	2.5	0.8 250 400	2.0 2.5 2.5	2.5	0.8 250 400	2.0 2.5 2.5	2.5	0.8 250 400	V V μΑ μΑ pF ns ns
OVERFLOW INHIBIT INPUT 0 V Input Current	Full	VI		200	250		200	250		200	250		200	250	μА
AC LINEARITY 10 Effective Bits11 In-Band Harmonics	+25°C	V		7.5			7.5			7.5			7.5		Bits
dc to 1.23 M H z dc to 9.3 M H z dc to 19.3 M H z Signal-to-N oise Ratio ¹² N oise Power Ratio ¹³	+25°C +25°C +25°C +25°C +25°C		48	55 50 44 47.6 37		48 46	55 50 44 47.6 37		48	55 50 44 47.6 37		48	55 50 44 47.6 37		dBc dBc dBc dBc dBc
DIGITAL OUTPUT Logic "1" Voltage Logic "0" Voltage	Full Full	VI VI	2.4		0.4	2.4		0.4	2.4		0.4	2.4		0.4	V
POWER SUPPLY ¹⁴ Positive Supply Current (+5.0 V) Supply Current (-5.2 V) Nominal Power Dissipation Reference Ladder Dissipation Power Supply Rejection Ratio ¹⁵	+25°C Full +25°C Full +25°C +25°C +25°C	VI		33 152 955 44 0.85	45 48 179 191		33 152 955 44 0.85	45 48 179 191		33 152 955 44 0.8	45 48 179 191		33 152 955 44 0.8	45 48 179 191	mA mA mA mA mW mW

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NOTES

$^9 \text{ENCODE}$ signal rise/fall times should be less than 30 ns for normal operation.

ABSOLUTE MAXIMUM RATINGS¹

ADSOLUTE MAXIMUS
Positive Supply Voltage (+V _S)+6 V
Analog to Digital Supply Voltage Differential (-V _S) 0.5 V
N egative Supply Voltage (-V _S)6 V
Analog Input Voltage
ENCODE Input Voltage0.5 V to +5 V
OVERFLOW IN H Input Voltage5.2 V to 0 V
Reference Input Voltage $(+V_{REF}-V_{REF})^2$ 3.5 V to +0.1 V
Differential Reference Voltage 2.1 V
Reference M idpoint Current ±4 mA
Digital Output Current 30 mA
Operating T emperature Range
AD 9012AQ/BQ/AJ/BJ25°C to +85°C
AD 9012SE/SQ/T E/T Q55°C to +125°C
Storage T emperature Range65°C to +150°C
Junction Temperature ³ +175°C
L ead Soldering T emperature (10 sec) +300°C

NOTES

¹Absolute maximum ratings are limiting values, to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability under any of these conditions is not necessarily implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

where

PD = power dissipation

 θ_{JA} = thermal impedance from junction to ambient (°C/W)

 θ_{IC} = thermal impedance from junction to case (°C/W)

 $t_A = ambient temperature (°C)$

 t_C = case temperature (°C)

typical thermal impedances are:

C eramic DIP $\dot{\theta}_{JA} = 42^{\circ}\text{C/W}$; $\dot{\theta}_{JC} = 10^{\circ}\text{C/W}$

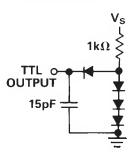
Ceramic LCC $\theta_{JA} = 50$ °C/W; $\theta_{JC} = 15$ °C/W

JLCC $\theta_{IA} = 59^{\circ}\text{C/W}$; $\theta_{IC} = 15^{\circ}\text{C/W}$.

Recommended Operating Conditions

	Input Voltage							
Parameter	Min	Nominal	Max					
-V _S	-5.46	-5.20	-4.94					
+V _S	+4.75	5.00	+5.25					
+V _{REF}	-V _{REF}	0.0 V	+0.1					
-V _{REF}	-2.1	-2.0	+V _{REF}					
Analog Input	-V _{REF}		+V _{REF}					

LOAD CIRCUIT



EXPLANATION OF TEST LEVELS Test Level

- I 100% production tested.
- II 100% production tested at +25°C, and sample tested at specified temperatures. AC testing done on sample basis.
- III Sample tested only.
- IV Parameter is guaranteed by design and characterization testing.
- V Parameter is a typical value only.
- VI All devices are 100% production tested at +25°C. 100% production tested at temperature extremes for extended temperature devices; guaranteed by design and characterization testing for industrial devices.

ORDERING GUIDE

Device	Linearity	Temperature Range	Package Option*		
AD 9012AQ AD 9012BQ AD 9012AJ AD 9012BJ AD 9012SQ AD 9012SE AD 9012T Q AD 9012T E	0.75 LSB 0.50 LSB 0.75 LSB 0.50 LSB 0.75 LSB 0.75 LSB 0.50 LSB	-25°C to +85°C -25°C to +85°C -25°C to +85°C -25°C to +85°C -55°C to +125°C -55°C to +125°C -55°C to +125°C -55°C to +125°C	Q-28 Q-28 J-28 J-28 Q-28 E-28A Q-28 E-28A		

*E = Leadless Ceramic Chip Carrier; J = Ceramic Leaded Chip Carrier; Q = Cerdip.

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD 9012 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



 $^{{}^{1}}M$ easured with Analog Input = 0 V.

²M easured by FFT analysis where fundamental is -3 dBc.

³Input slew rate derived from rise time (10% to 90%) of full-scale step input.

⁴Outputs terminated with two equivalent 'L S00 type loads. (See load circuit.)

 $^{^5}$ M easured from ENCODE into data out for LSB only.

⁶For full-scale step input, 8-bit accuracy is attained in specified time.

⁷R ecovers to 8-bit accuracy in specified time, after 150% full-scale input overvoltage.

⁸Output time skew includes high-to-low and low-to-high transitions as well as bit-to-bit time skew differences.

 $^{^{10}}$ M easured at 75 M SPS encode rate. H armonic data based on worst case harmonics. 11 A nalog input frequency = 1.23 M H z.

 $^{^{12}{\}rm R\,M\,S}$ signal to rms noise, including harmonics with 1.23 M Hz. analog input signal.

¹³N PR measured @ 0.5 M Hz. N oise Source is 250 mW (rms) from 0.5 M Hz to 8 M Hz.

 $^{^{14}}$ Supplies should remain stable within $\pm 5\%$ for normal operation.

 $^{^{15}\}text{M}$ easured at –5.2 V \pm 5% and +5.0 V \pm 5%.

Specifications subject to change without notice.

 $^{^{2}+}V_{REF} \ge -V_{REF}$ under all circumstances.

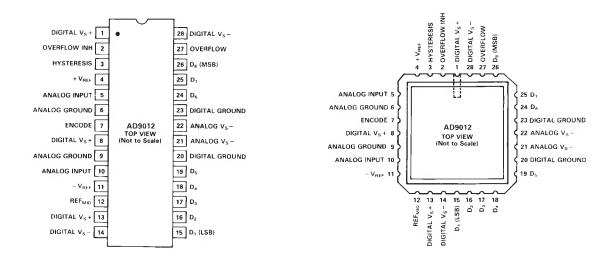
³M aximum junction temperature (t_j max) should not exceed +175°C for ceramic packages, and +150°C for plastic packages:

 $t_J = PD (\theta_{JA}) + t_A$ $PD (\theta_{JC}) + t_C$

FUNCTIONAL DESCRIPTION

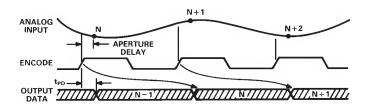
Pin#	Name	Description							
1 2	DIGITAL +V _S OVERFLOW INH	One of three positive digital supply pins (nominally +5.0 V). OVERFLOW INHIBIT controls the data output coding for overvoltage inputs (AIN \geq + V _{REF}).							
		ANALOG INPUT	OVERFLOW ENABLED (FLOATING) OF $D_1 D_2 D_3 D_4 D_5 D_6 D_7 D_8$	OVERFLOW INHIBITED (GND) OF $D_1 D_2 D_3 D_4 D_5 D_6 D_7 D_8$					
		$V_{IN} \ge + V_{REF}$ $V_{IN} < + V_{REF}$	1 0 0 0 0 0 0 0 0 0 X X X X X X X X X	0 1 1 1 1 1 1 1 1 1 0 X X X X X X X X X					
3	HYSTERESIS		is control voltage varies the comparator hyste -5.2 V to -2.2 V at the Hysteresis control pin						
4 5 6 7 8 9 10 11 12 13 14	+V _{REF} ANALOG INPUT ANALOG GROUND ENCODE DIGITAL +V _S ANALOG GROUND ANALOG INPUT -V _{REF} REF _{MID} DIGITAL +V _S DIGITAL -V _S	The most post One of two at One of two at TTL level en One of three One of two at The most neg The midpoint One of three	sitive reference voltage for the internal resistonalog input pins. Both analog input pins shounalog ground pins. Both analog ground pins scode command input. ENCODE is rising edgeositive digital supply pins (nominally +5.0 Nalog ground pins. Both analog ground pins should by gative reference voltage for the internal resistot tap on the internal resistor ladder. positive digital supply pins (nominally +5.0 Nalog ground gital supply pins (nominally -5.2 V)	r ladder. uld be connected together. should be connected together. ge sensitive. /). should be connected together. be connected together. or ladder. //).					
15 16-19 20 21, 22	D ₁ (LSB) D ₂ -D ₅ DIGITAL GROUND ANALOG -V _S	Digital data of Digital data of One of two done of two notes of two no	output. D ₁ (LSB) is the least significant bit of output. igital ground pins. Both digital grounds pins e egative analog supply pins (nominally –5.2 V	should be connected together.					
23 24, 25 26 27	DIGITAL GROUND D ₆ , D ₇ D ₈ (M SB) OVERFLOW	Digital data o Digital data o Overflow data	igital ground pins. Both digital ground pins s	f the digital output word. ervoltage ($V_{IN} > + V_{REF}$), if					
28	DIGITAL -V _S		egative digital supply pins (nominally –5.2 V)						

PIN DESIGNATIONS

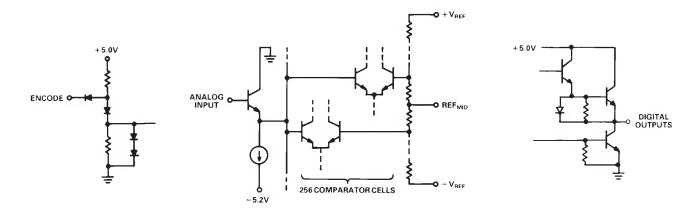


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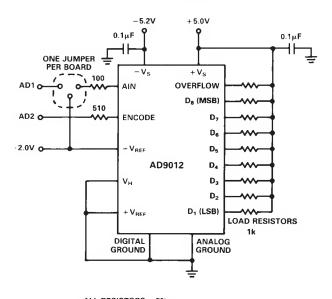
TIMING DIAGRAM



INPUT OUTPUT CIRCUITS

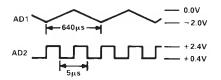


BURN-IN DIAGRAM

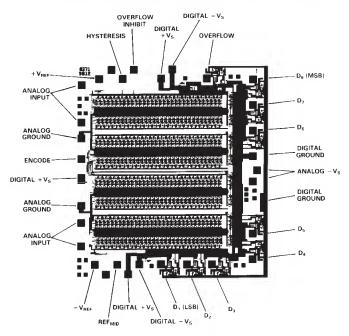


ALL RESISTORS ±5% ALL CAPACITORS ±20% ALL SUPPLY VOLTAGES ±5%

OPTION #1 (STATIC) AD1 = -2.0V; AD2 = +2.4V OPTION #2 (DYNAMIC) SEE WAVEFORMS



DIE LAYOUT AND MECHANICAL INFORMATION



Die Dimensions
M etalization
Backing None
Substrate Potential
Passivation Nitride
Die Attach Gold Eutectic (Ceramic)
Epoxy (Plastic)
Bond Wire 1-1.3 mil Gold; Gold Ball Bonding

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AD9012

APPLICATION INFORMATION

The AD 9012 is compatible with all standard TTL logic families. However, to operate at the highest encode rates, the supporting logic around the AD 9012 will need to be equally fast. Two possible choices are the AS and the ALS families. Whichever of the TTL logic families is used, special care must be exercised to keep digital switching noise away from the analog circuits around the AD 9012. The two most critical items are the digital supply lines and the digital ground return.

The input capacitance of the AD 9012 is an exceptionally low 16 pF . This allows the use of a wide range of input amplifiers, both hybrid and monolithic. To take full advantage of the 160 MHz input bandwidth of the AD 9012, a hybrid amplifier like the AD 9610/AD 9611 will be required. For those applications that do not require the full input bandwidth of the AD 9012, some of the more traditional monolithic amplifiers, like the AD 846, should work very well. O verall performance with monolithic amplifiers can be improved by inserting a 40 Ω resistor in series with the amplifier output.

The output data is buffered through the TTL compatible output latches. In addition to the latch propagation delay (t_{PD}) , all data is delayed by one clock cycle, before becoming available at the outputs. Both the analog-to-digital conversion cycle and the data transfer to the output latches are triggered on the rising edge of the TTL-compatible ENCODE signal (see timing diagram).

The AD 9012 also incorporates a HYST ERESIS control pin which provides from 0 mV to 10 mV of additional hysteresis in the comparator input stages. Adjustments in the HYST ERESIS control voltage may help to improve noise immunity and overall performance in harsh environments.

The OVERFLOW INHIBIT pin of the AD 9012 determines how the converter handles overrange inputs (AIN \geq + V_{REF}). In the "enabled" state (floating at –5.2 V), the OVERFLOW output will be at logic HIGH and all other outputs will be at logic LOW for overrange inputs (return-to-zero operation). In the "inhibited" state (tied to ground), the OVERFLOW output will be at logic LOW for overrange inputs, and all other digital outputs will be at logic HIGH (nonreturn-to-zero operation).

The AD 9012 provides outstanding error rate performance. This is due to tight control of comparator offset matching and a fault tolerant decoding stage. Additional improvements in error rate are possible through the addition of hysteresis (see HYSTER-ESIS control pin). This level of performance is extremely important in fault sensitive applications such as digital radio (QAM).

D ramatic improvements in comparator design and construction give the AD 9012 excellent dynamic characteristics, namely SNR (signal-to-noise ratio). The 160 MHz input bandwidth and low error rate performance give the AD 9012 an SNR of 47 dB with a 1.23 MHz input. High SNR performance is particularly important in broadcast video applications where signals may pass through the converter several times before the processing is complete. Pulse signature analysis, commonly performed in advanced radar receivers, is another area that is especially dependent on high quality dynamic performance.

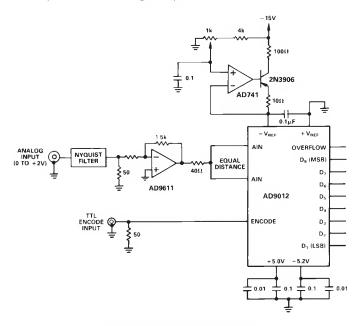
LAYOUT SUGGESTIONS

D esigns using the AD 9012, like all high-speed devices, must follow a few basic layout rules to insure optimum performance. Essentially, these guidelines are meant to avoid many of the problems associated with high-speed designs. The first requirement is for a substantial ground plane around and under the AD 9012. Separate ground plane areas for the digital and analog components may be useful, but the separate grounds should be connected together at the AD 9012 to avoid the effects of "ground loop" currents.

The second area that requires an extra degree of attention involves the three reference inputs, $+V_{REF}$, REF_{MID}, and $-V_{REF}$. The $+V_{REF}$ input and the $-V_{REF}$ input should both be driven from a low impedance source (note that the $+V_{REF}$ input is typically tied to analog ground). A low drift amplifier should provide satisfactory results, even over an extended temperature range. A djustments at the REF_{MID} input may be useful in improving the integral linearity by correcting any reference ladder skews.

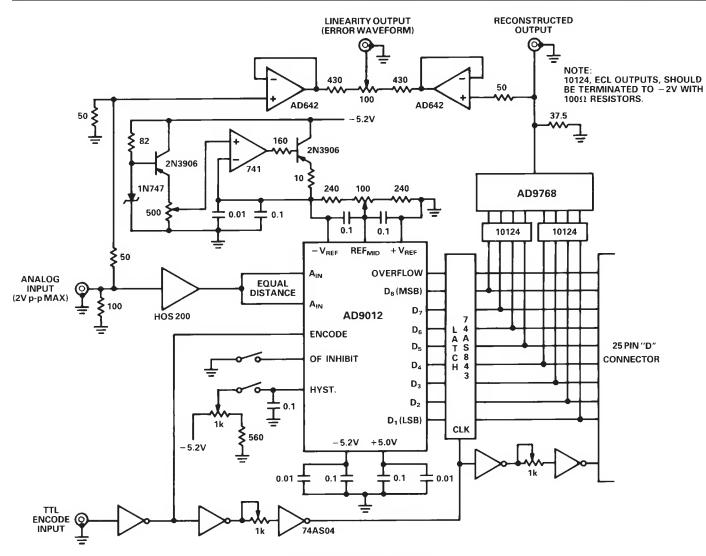
The reference inputs should be adequately decoupled to ground through 0.1 μF chip capacitors to limit the effects of system noise on conversion accuracy. The power supply pins must also be decoupled to ground to improve noise immunity; 0.1 μF and 0.01 μF chip capacitors should be very effective.

The analog input signal is brought into the AD 9012 through two separate input pins. It is very important that the two input pins be driven symmetrically with equal length electrical connections. Otherwise, aperture delay errors may degrade converter performance at high frequencies.

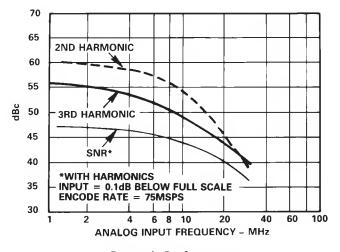


Typical AD9012 Application

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AD9012 Evaluation Circuit



Dynamic Performance

REV. B -7-

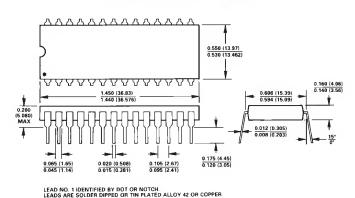
OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

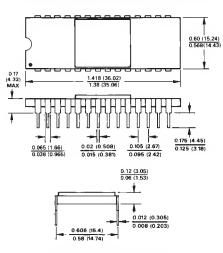
28-Pin PLCC Package

0.056 (1.42) × 45° 0.042 (1.07) × 45° 0.048 (1.23) 0.048 (1.23) 0.048 (1.158) 0.045 (11.43) 0.045 (11.43) 0.045 (11.43) 0.045 (11.43) 0.046 (11.43) 0.056 (11.43) 0.047 (1.07) × 45° 0.048 (1.23) 0.048 (1.22) 0.048 (1.23) 0.048 (1.23) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43) 0.050 (11.43)

28-Pin Plastic DIP Package

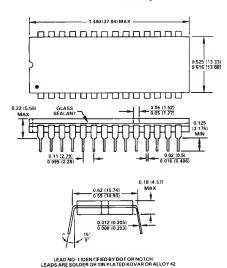


28-Pin Ceramic Side-Brazed DIP

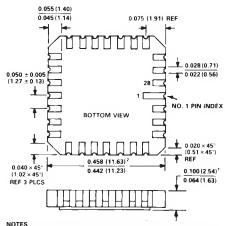


LEAD NO. 1 (DENTIFIED BY DOT OR NOTCH LEADS ARE GOLD PLATED (50 MICROINCHES MIN) KOVAR OR ALLOY 42

28-Pin Cerdip



28-Pin Leadless Chip Carrier



NOTES
'THIS DIMENSION CONTROLS THE OVERALL PACKAGE THICKNESS.
'APPLIES TO ALL FOUR SIDES.
TERMINALS ARE GOLD PLATED OR SOLDER DIPPED.

REV. B